

SYMBOL	VARIATIONS												
STIVIBOC	AA			AB			AC			AD			
	MIN	MAX	NOTE	MIN	MAX	NOTE	MIN	MAX	NOTE	MIN	MAX	NOTE	
Δ	1.040	1.080	17	1.140	1.180	17	1.240	1.280	17	1.340	1.380	17	
Ε	1.040	1.080	17	1.140	1.180	17	1.240	1.280	17	1.340	1.380	17	
Q	0.045	0.075	8	0.045	0.075	8	0.045	0.075	8	0.045	0.075	8	
			10			10			10			10	
М	10		4	11		4	12		4	13		4	
Ν		84	5	_	96	5	_	108	5	_	144	5	
S	.050 BASIC			0.000 BASIC			0.050 BASIC			0.000 BASIC			
NOTE	1,2,3,6.9,16,21												
REF	Item 10-294												
ISSUE	Α												
	A	AE		AF		NOTE	AG		NOTE	AH		NOTE	
	MIN	MAX	NOTE	MIN	MAX	HOIE	MIN	MAX	NOIE	MIN	MAX	, TOIE	
D	1.440	1.480	17	1.540	1.580	17	1.640	1.680	17	1.740	1.780	17	
Ε	1.440	1.480	17	1.540	1.580	17	1.640	1.680	17	1.740	1.780	17	
Q	0.045	0.075	8	0.045	0.075	8	0.045	0.075	8	0.045	0.075	8	
			10		<u> </u>	10			10			10	
М	1	4	4	1	5	4	1	16	4	1	7	4	
N	-	160	5		176	5		220	5	_	240	5	
S	0.050 BASIC			0.000 BASIC		<u> </u>	0.050 BASIC			0.000 BASIC			
NOTE	1,2,3,6,						 						
REF	item 10)-294											
ISSUE	Α												
Ì ,			1	1 ^~		T			1	AM			
	AJ		NOTE AK		MAX NOTE	AL MIN MAX		NOTE	MIN MAX		NOTE		
D	1.840	1.880	17	MIN 1.940	1.980	17	2.040	2.080	17	2.140	2.180	17	
E	1.840	1.880	17	1.940	1.980	17	2.040	2.080	17	2.140	2.180	17	
Q	0.045	0.075	8	0.045	0.075	8	0.045	0.075	8	0.045	0.075	8	
6	0.045	0.073	10	0.040	0.073	10	0.045	0.075	10	0.045	0.073	10	
M		 8	4		 9	4	20		4	21		4	
N		260	5		280	5	<u> </u>	300	5		320	5	
S		<u> </u>	 				 		+-	<u> </u>	ــــــــــــــــــــــــــــــــــــــ	+	
NOTE	0.050 BASIC 0.000 BASIC 0.050 BASIC 0.000 BASIC 1,2,3,6,9,16,21												
REF	item 10						·						
ISSUE	A	F474		 									
-3306	JEDEC		١٠٠	PAMIC PI	N GDID AT	DAV	ISSUE	DATE	1				
SOLID	SOLID STATE PRODUCT			CERAMIC PIN GRID ARRAY PACKAGE FAMILY, S-C-GA			В		MS-017 PAGE 2 C			OF 4	
	OUTLINE			(.100' PITCH, CAVITY DOWN)				JUNE 1993	E]			<u> </u>	

)

SYMBOL	VARIATIONS											
01111000	BA			BB			ВС			BD		
	MIN	MAX	NOTE	MIN	MAX	NOTE	MIN	MAX	NOTE	MIN	MAX	NOTE
D	1.040	1.080	17	1.140	1.180	17	1.240	1.280	17	1.340	1.380	17
E	1.040	1.080	17	1.140	1.180	17	1.240	1.280	17	1.340	1.380	17
Q	0.0	0.0	22	0.0	0.0	22	0.0	0.0	22	0.0	0.0	22
М	1	0	4	1	1 4		12		4	13		4
N	-	84	5	_	96	5		108	5	- 144		5
S	.050 [BASIC		0.000 BASIC			0.050 BASIC			0.000 BASIC		
NOTE	1,2,3,6,9,16,21,22											
REF	Item 10-315											
ISSUE B												
1												
	BE		NOTE		F	NOTE		G	NOTE	BI		NOTE
D	MIN 1.440	MAX 1.480	17	MIN 1.540	1.580	35	MiN	MAX	,-	MIN	MAX	
E	1.440	1.480	17	1.540	1.580	17	1.640 1.640	1.680 1.680	17	1.740	1.780	17
8	0.0	0.0	22	0.0	0.0	22	0.0	0.0	22	0.0	0.0	22
M		4	4		5	4		16	4	0.0		4
N		160	5		176	5		220	5		240	5
S	0.050 BASIC			0.000 BASIC		-	0.050 BASIC			0.000 BASIC		
NOTE		9,16,21,2	2									
REF	Item 10											
ISSUE	В											
				· · · · · · · · · · · · · · · · · · ·								
	BJ		NOTE		K	1.0~	E	3L		В	М	
	MIN	MAX	NOIE	MIN	MAX	NOTE	MIN	MAX	NOTE	MIN	MAX	NOTE
D	1.840	1.880	17	1.940	1.980	17	2.040	2.080	17	2.140	2.180	17
Ε	1.840	1.880	17	1.940	1.980	17	2.040	2.080	17	2.140	2.180	17
Ø	0.0	0.0	22	0.0	0.0	22	0.0	0.0	22	0.0	0.0	22
М	1	8	4	١	9	4	2	20		21		4
Z	_	260	5	-	280	5	_	300	5	-	320	5
S	0.050	0.050 BASIC		0.000 BASIC			0.050 BASIC			0.000 BASIC		
NOTE	TE 1,2,3,6,9,16,21,22											
REF	Item 10-315											
ISSUE	В											
	JEDEC		CE	CERAMIC PIN GRID ARRAY			ISSUE	DATE				
SOLID STATE PRODUCT			PACKAGE FAMILY, S-C-GA			В			1S- 017	PAGE 3 OF 4		
OUTLINE (.100" PITCH, CAVITY DOWN) 1993												

NOTES:

- 1. Dimensioning & tolerancing per ANSI Y14.5M-1982.
- 2. Refer to applicable symbol list.
- 3. Terminal position designation per JESD 95-1.
- 4. Symbol "M" is the in matrix size.
- 5. Symbol "N" is the maximum allowable number of pins.
- 6. 11X11 and 12X12 matrix sizes shown for illustration only.

 $\sqrt{7.}$ Dimension "A" does not include heatsinks or other attached features.

8.\(\) The standoff shall be located on the pin matrix diagonals. The major dimension of the standoff feature should be .045" minimum.

The seating plane is the outer standoff surface facing away from the ceramic body for variations AA-AM. The seating plane is the ceramic body surface for variations BA-BM.

Dimension "Q" Is measured from the ceramic body surface to the outer standoff surface. See APPLICATION NOTE for variations AA-AM,

11 All pins shall be on the .100° grid.

 $\cancel{12}$ -C- is the plane of pin to package interface.

Pin tips should have a radius or chamfer. See APPLICATION NOTE.

14. See APPLICATION NOTE.

15. This dimension allows a 750 microinch thick coating for solder dipped parts. See APPLICATION.

16. There must be some type of A1 corner identification on both top and bottom surfaces of the package. ID type is optional and may consist of notches, ID plns, metallized markings or other features. The features used on each surface may be of differing types.

10. There shall be .015" minimum spacing between any two metal features on the package surface.

Dimensions "D" and "E" do not include ceramic protrusions. Such protrusions may not extend more than .003" on any side. Comers and edges of the package body may have chamfers for mechanical protection or identification.

19 This dimension defines the maximum size for the pin braze pads.

 \dot{x} S is measured with respect to -A- and -B-.

21. All dimensions in INCHES.

 $_{
m \Delta}$ There are no standoff pins on variations BA through BM.

APPLICATION NOTES:

- For applications where a PGA package is used in a socket, the following requirements may apply:
 - a. Pin tips shall have a radius or chamfer.
 - b. Standoff height shall be in the range .055"/.045", if the standoff pin is used.
 - c. Minimum pin length (dimension "L") shall be .120".
 - d. Maximum pin diameter including finish should be .020".
- For military applications the pin length (dimension "L") range may be restricted to .120"/.140".

JEDEC	CERAMIC PIN GRID ARRAY	ISSUE	DATE			
SOLID STATE PRODUCT	PACKAGE FAMILY, S-C-GA	В	JUNE 1993	MS-017	PAGE 4 of 4	
	(.100" PITCH, CAVITY DOWN)					